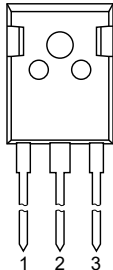
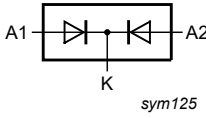




Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$I_F = 15\text{ A}$ ; $V_R = 400\text{ V}$ ; $di_F/dt = 500\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>	-	34	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	 <p>TO-247 (SOT429)</p>	 <p>sym125</p>
2	K	cathode		
3	A2	anode 2		
mb	mb	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

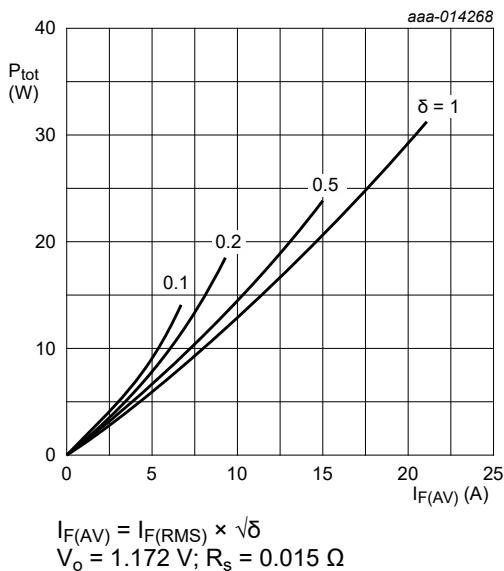
Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV415W-600P	TO247	BYV415W-600PQ	Tube	30	SOT429	25-Mar-2013

## 7. Limiting values

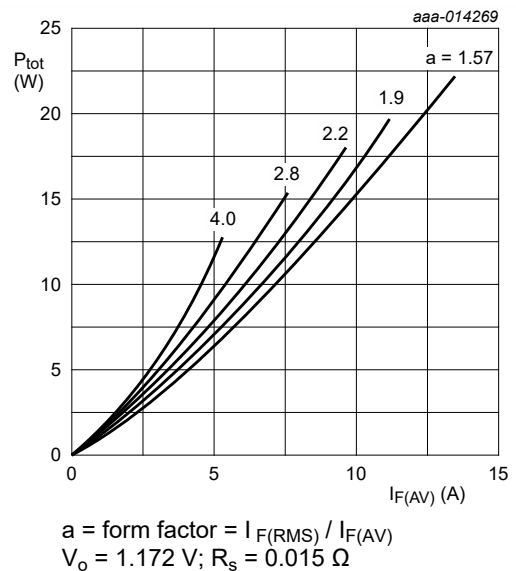
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	DC	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 127\text{ }^\circ\text{C}$ ; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	-	15	A
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; $T_{mb} \leq 117\text{ }^\circ\text{C}$ ; square-wave pulse; both diodes conducting	-	30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 127\text{ }^\circ\text{C}$ ; Square-wave pulse	-	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; per diode; Fig. 4	-	150	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; per diode; Fig. 4	-	165	A
$T_{stg}$	storage temperature		-65	175	$^\circ\text{C}$
$T_j$	junction temperature		-	175	$^\circ\text{C}$



**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

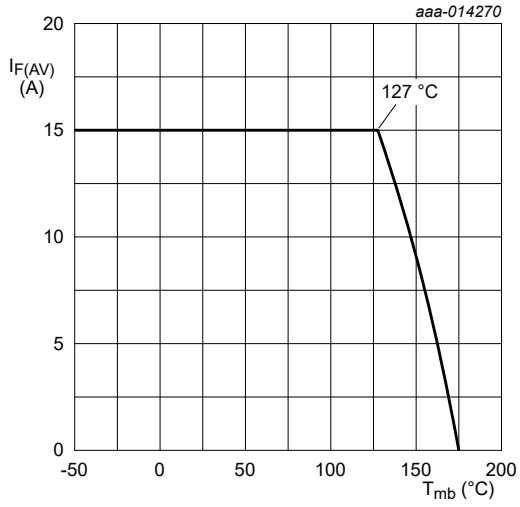


Fig. 3. Forward current as a function of mounting base temperature; maximum values

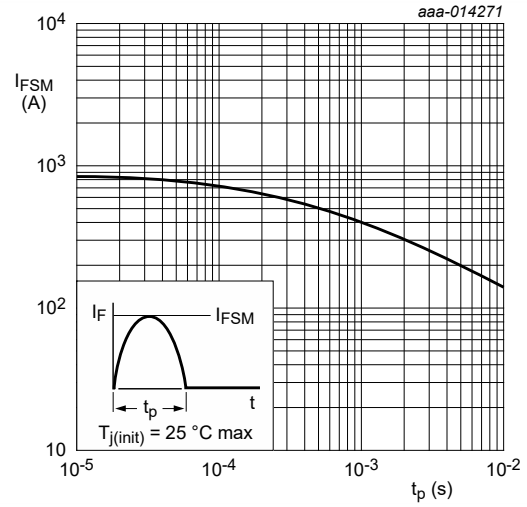


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; per diode; <a href="#">Fig. 5</a>	-	1.2	2	K/W
		with heatsink compound; both diodes conducting	-	0.65	1.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

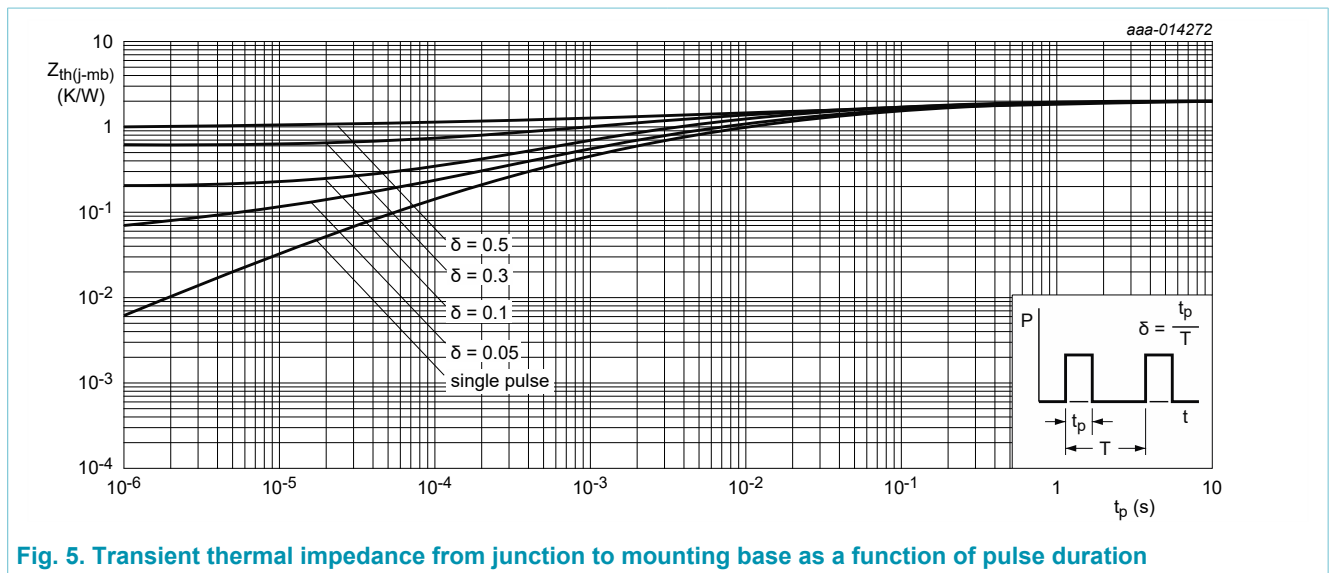


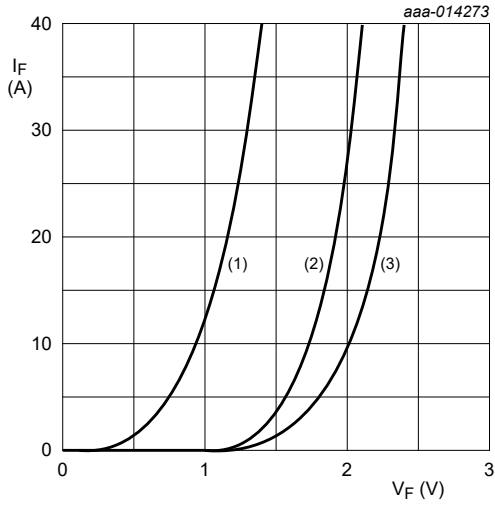
Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 9. Characteristics

**Table 6. Characteristics**

characteristics are per diode unless otherwise stated

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 15\text{ A}; T_j = 25\text{ °C};$ <a href="#">Fig. 6</a>	-	1.4	2.1	V
		$I_F = 15\text{ A}; T_j = 150\text{ °C};$ <a href="#">Fig. 6</a>	-	1.1	1.8	V
$I_R$	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ °C}$	-	-	10	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 150\text{ °C}$	-	-	500	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	25	50	ns
		$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	45	-	ns
		$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C};$ <a href="#">Fig. 7</a>	-	65	-	ns
		$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	34	-	ns
$I_{RM}$	peak reverse recovery current	$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	5.5	-	A
		$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C};$ <a href="#">Fig. 7</a>	-	9.7	-	A
$Q_r$	recovered charge	$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	125	-	nC
		$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C};$ <a href="#">Fig. 7</a>	-	318	-	nC



$V_o = 1.172 \text{ V}; R_s = 0.015 \Omega$   
 (1)  $T_j = 150 \text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 150 \text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

Fig. 6. Forward current as a function of forward voltage

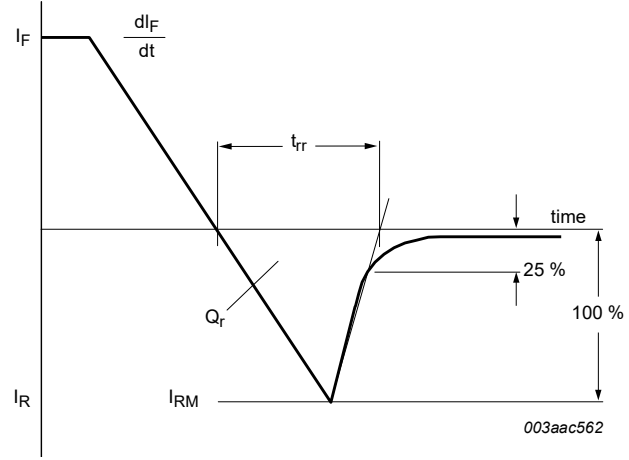
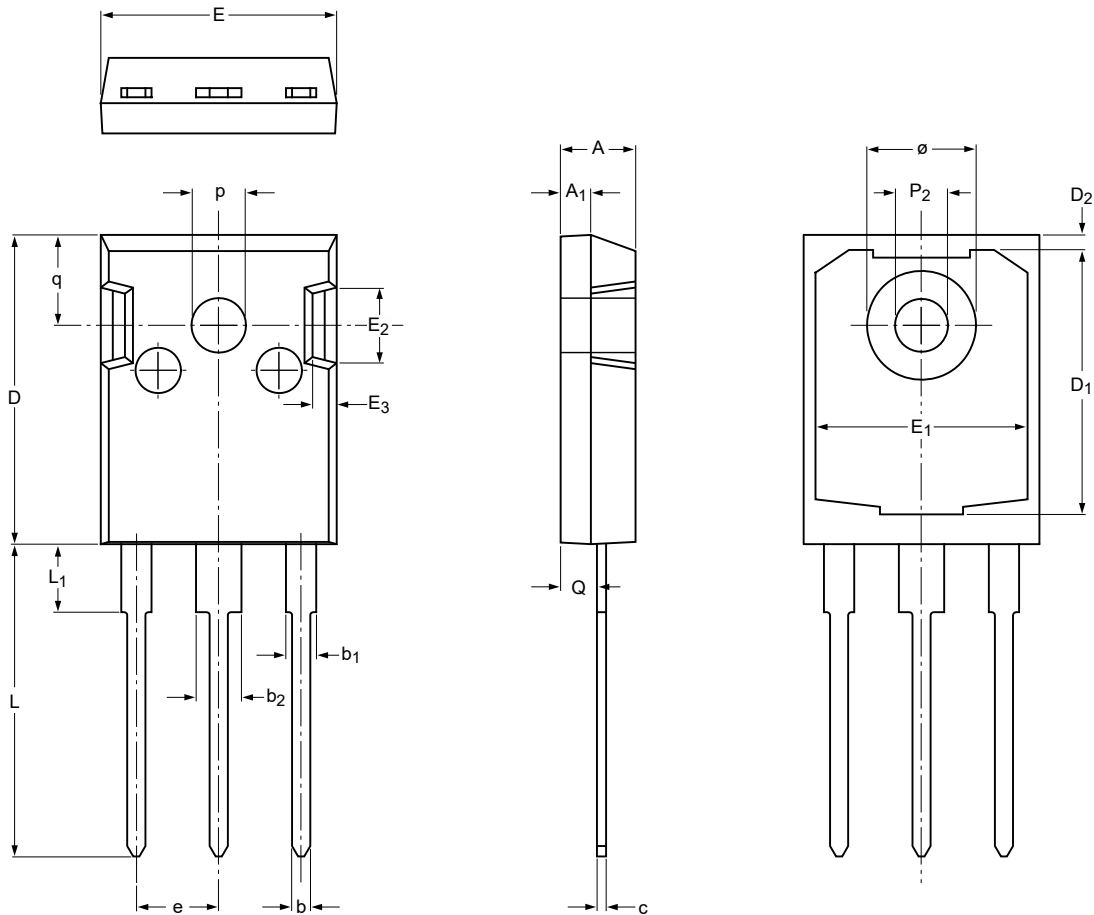


Fig. 7.

10. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247 SOT429



Dimensions (mm are the original dimensions)

Unit <sup>(1)</sup>	A	A <sub>1</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	D	D <sub>1</sub>	D <sub>2</sub>	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	e <sup>(1)</sup>	L	L <sub>1</sub>	P <sub>2</sub>	p	Q	q	ø	
max	5.20	2.10	1.40	2.20	3.20	0.70	20.6	17.68	1.20	15.75	14.22	5.20	1.80	5.45	20.90	4.75	3.60	3.70	2.60	6.18	7.30	
nom																						
min	4.70	1.90	1.00	1.80	2.80	0.50	20.3	17.28	0.80	15.45	13.82	4.80	1.40	20.40	4.25	3.40	3.50	2.20	5.78	7.10		

Note

1. Basic spacing between centers.

sot429\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT429		TO-247			-04-09-14- 13-03-25

Fig. 8. Package outline TO-247 (SOT429)



## 11. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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Date of release: 26 November 2019

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